

II. CLAIM AMENDMENTS

1. (Original) A method of forming a high resolution LED array comprising the steps of:

providing a plurality of LED chips to form the LED array;

inward biasing an electrode of an LED located at each end of each chip by a predetermined amount;

reducing a size of each LED chip by removing, at each end of each chip, an amount of chip material substantially equal to the predetermined amount; and

forming the array by placing each chip end to end with a gap between each chip, wherein the gap is suitably large for placement accuracies and a consistent pitch of approximately 21.2 μm is maintained between each LED on each chip.

2. (Original) The method of claim 1 wherein the step of inward biasing the electrode comprises positioning the electrode approximately 2.6 μm from the edge.

3. (Original) The method of claim 1 wherein the predetermined amount is approximately 2.6 μm .

4. (Original) The method of claim 1 wherein the step of inward biasing includes shifting a centroid of light emitted from the LED to a side of the chip near the end of the chip, wherein an emitted light profile of the LED is varied to allow the gap between adjacent chips to be larger while a consistent distance is maintained between adjacent pixels on each chip.

5. (Original) The method of claim 1 wherein the step of inward biasing includes biasing a centroid of each LED at the end of each chip toward the edge.

6. (Previously Presented) The method of claim 1 wherein the high resolution LED array formed comprises an LED array providing at least 1200 spots per inch ("SPI").

7 - 12 (Cancelled)

13. (Previously Cancelled)

14 - 22 (Cancelled)